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Brighten up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ CHIP PCB LED w/ IC
- ▶ 0404 (1010) IC 0.50t (5 pins)
- ▶ Red/Green/Blue

Release Date: 15 May 2025 Version: A1.1

NOM68S99IC



0404 (1010) IC-Integrated



RoHS
Compliant

FEATURES:

- **Package:** PCB Top View Package with Integrated IC
- **R/G/B Output Current (typ.):** 5mA
- **Supply Voltage:** +3.3~+5.5V
- **Luminous Intensity (typ.):** 65/85/20mcd*
- **Colour:** Red/Green/Blue
- **Lens Colour:** Water Clear
- **IC Feature:** Programmable IC and RGB LED chip integrated 0404 (1010) package. Data Transmission by 2 Data Inputs. 24-bit data transfer rate. The data transmission frequency can reach 800Kbps. Support Sleep (Power Saving) Mode, the quiescent current is less than 5µA (typ.). Support 16-level current gain control (dimming control).
- **Soldering Methods:** Reflow soldering
- **ESD Level:** 2kV
- **MSL Level:** acc. to JEDEC Level 4
- **Packing:** 8mm tape with max.4000pcs/reel, ø178mm (7")

* in order of Red/Green/Blue



Support sleep/wake up mode. In sleep mode the LED's current was lower than 5µA

APPLICATIONS:

- Telecommunication
- Indicator
- Home Appliance
- Decoration Lighting
- Full Colour LED Strip
- Gaming Device
- Guardrail Tube
- LED Screen

CHARACTERISTICS:

Absolute Maximum Characteristics (T_a=25°C)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{DD}	6.5	V
Power Dissipation	P _D	400	mW
Maximum Output Current	I _{LED}	5	mA
Operation Temperature	T _{OPT}	-40~+85	°C
Storage Temperature	T _{STG}	-65~+120	°C
Soldering Temperature	T _{SOL}	Reflow: 210 for 5 sec.	°C

Electrical & Optical Characteristics (T_a=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Supply Voltage	V _{DD}	3.3	5.0	5.5	V	---
Operation Current (with IC)	I _{DD1}	---	1	---	mA	R/G/B without load @V _{DD} =5V
Operation Current (with IC)	I _{DD2}	---	0.6	---	mA	R/G/B without load @V _{DD} =3.3V
Sleep Mode Current	I _{sleep}	---	5	---	μA	---
Input High "H" of DI, BI	V _{IH}	0.7*V _{DD}	---	V _{DD} +0.4	V	---
Input Low "L" of DI, BI	V _{IL}	-0.4	---	0.2*V _{DD}	V	---
Output High "H" of DO	V _{OH}	4.5	---	---	V	I _{OH} =3mA
Output Low "L" of DO	V _{OL}	---	---	0.4	V	I _{OL} =3mA
R/G/B Sink Current	I _{sink}	2.9	3.0	3.1	mA	Max.3mA option
		4.8	5.0	5.2	mA	Max.5mA option
R/G/B Current Gain	G _{level}	---	3/17	---	mA/level	Max.3mA option
		---	5/17	---	mA/level	Max.5mA option
DI / BI Input Leakage	I _{leak}	---	---	1	μA	V _{DI} =V _{BI} =V _{DD} =5V
R/G/B Off Leakage Current	I _{off}	---	---	1	μA	V _{R/G/B} =5V PWM off

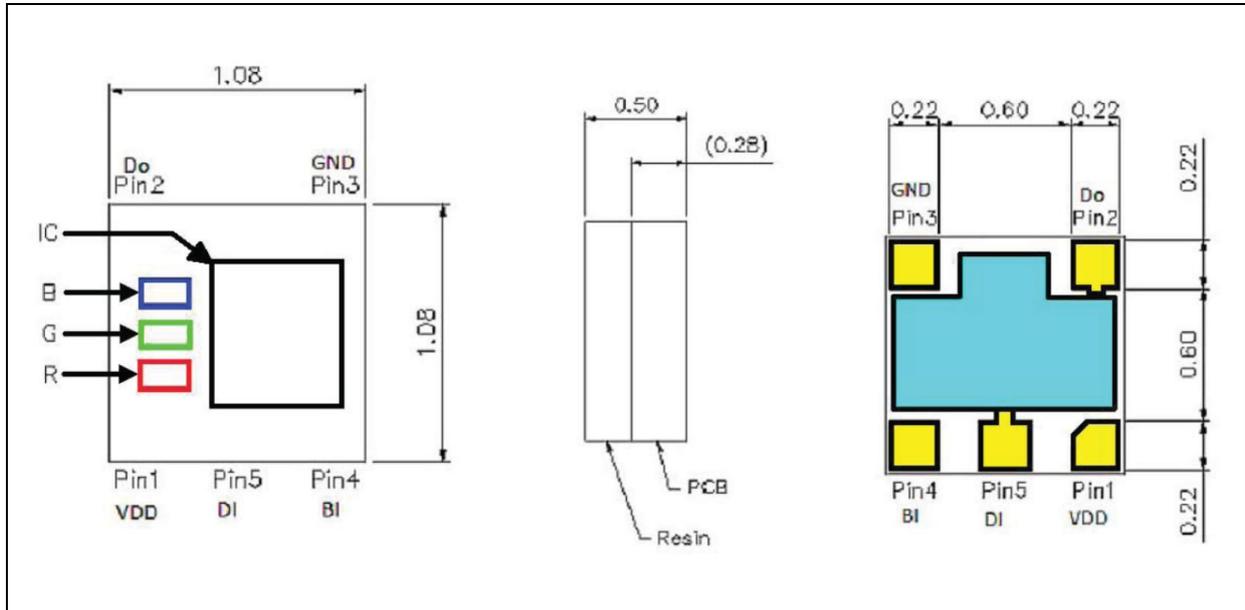
CHARACTERISTICS:

 Electrical & Optical Characteristics ($T_a=25^\circ\text{C}$)

Parameter		Symbol	Values			Unit	Test Condition
			Min.	Typ.	Max.		
Propagation Delay Time		t_{PLZ}	---	---	80	ns	DI → DO Load=30pF
		t_{PZL}	---	---	80	ns	
Rising Time		t_{THL}	---	15	---	ns	DI → DO Load=30pF
Falling Time		t_{TLH}	---	15	---	ns	
Rising Time		t_R	---	50	---	ns	$I_{SK(R/G/B)}=3/5\text{mA}$ Load=30pF
Falling Time		t_F	---	50	---	ns	
Data Rate		F_{data}	---	800	---	KHz	---
Dominant Wavelength	Red	λ_d	---	624	---	nm	$I_F=5\text{mA}$
	Green		---	523	---		
	Blue		---	470	---		
Spectrum Radiation Bandwidth	Red	$\Delta\lambda$	---	18	---	nm	$I_F=5\text{mA}$
	Green		---	35	---		
	Blue		---	25	---		
Luminous Intensity	Red	I_v	---	65	---	mcd	$I_F=5\text{mA}$
	Green		---	85	---		
	Blue		---	20	---		

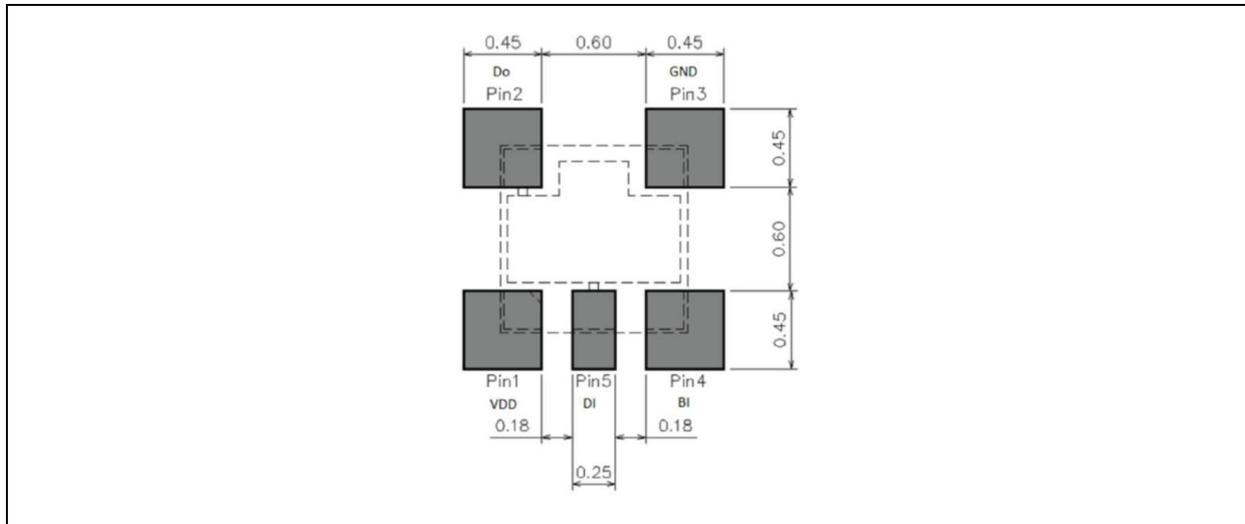
OUTLINE DIMENSION:

Package Dimension:



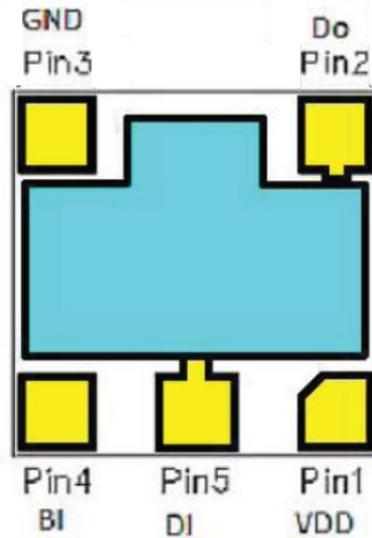
1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

PIN CONFIGURATION:



No.	Symbol	Function Description
1	VDD	Power Supply
2	DO	Control Data Signal Output
3	GND	Ground
4	BI	Backup Data Signal Input.* (Single Signal Wiring Diagram: BI is connected to GND)
5	DI	Control Data Signal Input

* Support BI backup input data line to prevent data input failure from malfunction DL.

FUNCTION DESCRIPTION:

1. Pre-design Stage:

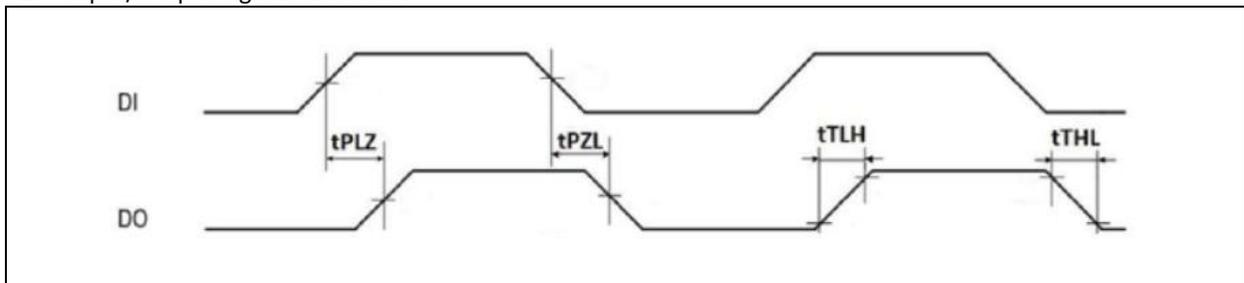
Emitted colour sequence: Red, Gren, Blue

In practical circuit applications, it is crucial to connect the signal input and output pins of the integrated circuit (IC) to their respective terminals. Additionally, for enhanced stability of the IC chip, it is necessary to include capacitance between displays.

For short display transmission distances, it is recommended to connect series protection resistor (approximately 470 ohms) at both the input and output ends of the clock line signal.

In cases where the display transmission distance is longer, especially for modules or specialized products, variations in wire type and transmission distance may occur. As a result, slight differences in grounding protection resistance at both ends of the clock line signal should be anticipated and addressed to ensure consistent performance in practical usage.

2. Input/Output Signals Relations:



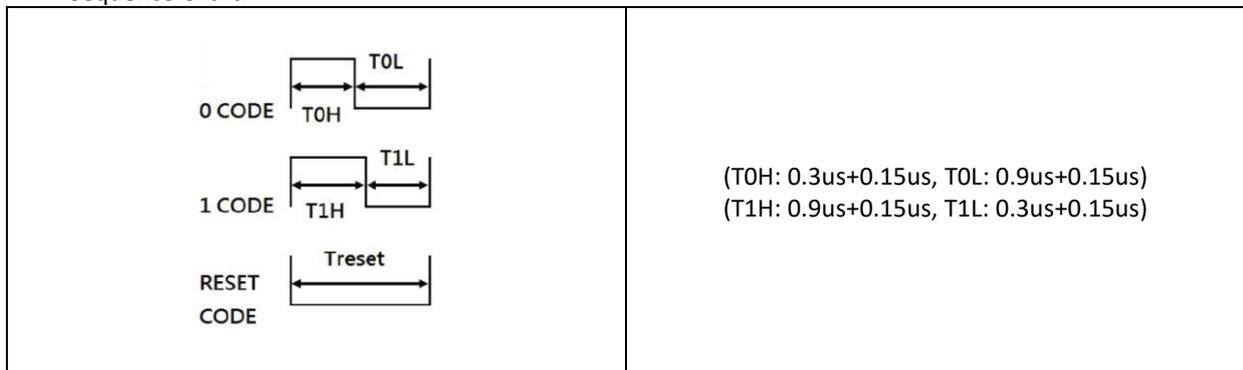
3. Data Transfer Protocol:



The single wire data transfer protocol supports 24-bit data for each LED RGB display data refresh. The IC receives 24-bit data and passes the remaining data to the next LED. The 24-bit data consist of red, green, and blue data, each with 8-bit width, and are transferred with MSB first.

The transferred data are recognized based on the pulse widths received by the IC. A low bit 0 is represented by a 0.3µs high pulse followed by a 0.9µs low pulse. A high bit 1 is represented by a 0.9µs high pulse followed by a 0.3µs low pulse. A low pulse ≥ 200µs is used to issue a reset command to the IC to start a new cycle of serial commands.

4. Sequence Chart:



5. Sleep and Power Saving Mode:

NOM68S99IC supports sleep/wake-up modes for power-saving purpose. When receiving 24-bit 0's RGB data, 8-bit 0x5A special data, and a reset command, NOM68S99IC will enter sleep mode. In sleep mode, the built-in oscillator and associated circuitry is disabled. The quiescent current of NOM68S99IC is less than 2µA (typ.) in sleep mode.

A sleeping NOM68S99IC wakes up from sleep mode when detecting an input rising edge on DI or BI pin. Normally a positive pulse on DI or BI pin can be used as a wake-up trigger. After waking up, all sleeping circuits in NOM68S99IC return to normal working mode within 1ms. To wake-up the next cascaded NOM68S99IC, the received positive pulse on DI pin is passed to DO pin, which connected to DI pin of the next NOM68S99IC, and in turn wakes up the next NOM68S99IC. Hence, all cascaded sleeping NOM68S99ICs can wake up successively.

Since it takes 1ms for a sleeping NOM68S99IC returning to normal functioning mode, it is recommended for MCU to wait for 1ms to send display data and commands after issuing a wake-up pulse. In case a mal-functioned NOM68S99IC exists in an LED strip, the one next to the mal-functioned NOM68S99IC determines the sleep/wake-up mode through BI pin, instead of DI pin.

In an LED strip, it is possible to set certain NOM68S99ICs active, while the others in sleep mode. As an example, the following commands are for two leading active NOM68S99ICs and other sleeping NOM68S99ICs.



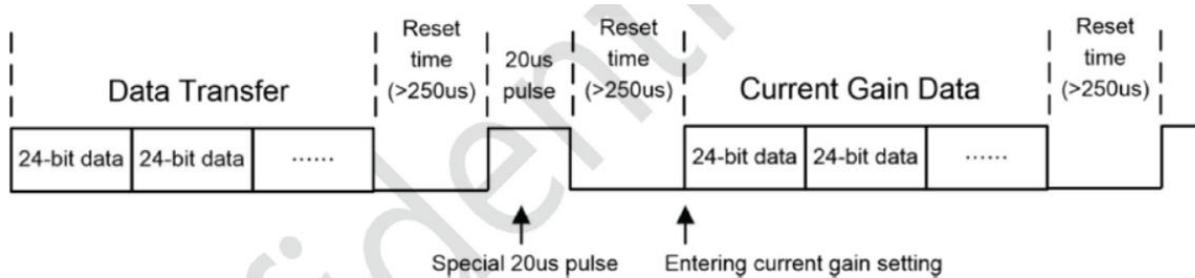
As an example of sleep/wake-up commands shown below, the first NOM68S99IC is kept active and the remaining NOM68S99ICs enter sleep mode by 24-bit 0's and an ending 0x5A byte. Later on, a positive pulse wakes up all sleeping NOM68S99ICs.



6. Dimming Control:

NOM68S99IC supports an 16-level current gain control to adjust sink current of R/G/B channels. This feature enables dimming control of LED lighting. Each of the red, green, and blue channels can be controlled individually, which in turn not only save power consumption, but also fine-tune the color temperature of R/G/B LEDs.

To set the current gain of NOM68S99IC's R/G/B channels, a special pulse must be issued by MCU before setting the current gain levels, as shown below.



After a reset pulse following normal data transfer, if a 20us positive pulse is issued with another reset pulse, NOM68S99IC is forced into a special mode to interpret following 24-bit data as current gain setting data. Each of the 24-bit data comprises 4-bit gain values of R/G/B channels, as shown below.

S23	S22	S21	S20	S19	S18	S17	S16	S15	S14	S13	S12	S11	S10	S9	S8	S7	S6	S5	S4	S3	S2	S1	S0
0	0	0	0	R[3]	R[2]	R[1]	R[0]	0	0	0	0	G[3]	G[2]	G[1]	G[0]	0	0	0	0	B[3]	B[2]	B[1]	B[0]

The maximum output current of each R/G/B channels is then determined as below (ISK=3mA or 5mA).

$$R_{\text{sink}} = ISK * (R[3]*10/17 + R[2]*4/17 + R[1]*2/17 + R[0]*1/17)$$

$$G_{\text{sink}} = ISK * (G[3]*10/17 + G[2]*4/17 + G[1]*2/17 + G[0]*1/17)$$

$$B_{\text{sink}} = ISK * (B[3]*10/17 + B[2]*4/17 + B[1]*2/17 + B[0]*1/17)$$

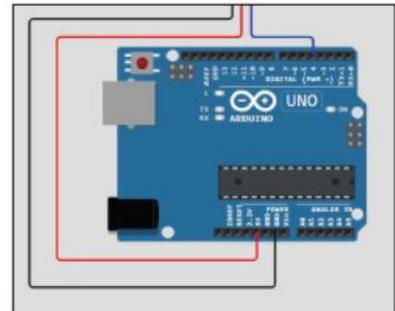
By default, R[3:0] = G[3:0] = B[3:0] = 0x0F.

Recommended programming flow:

After system power-on, MCU should send data 0 first (dark mode) for all LEDs in the strip, then MCU can deliver normal display data or execute current gain (dimming) command to LEDs.

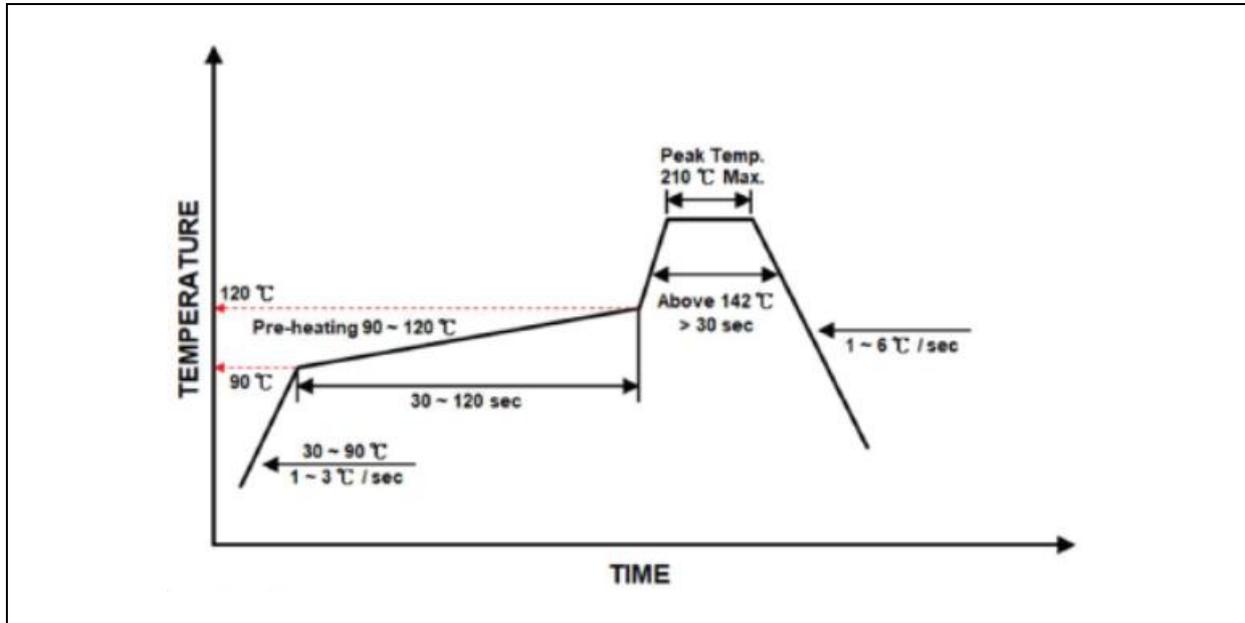
7. Sample Code:

```
// Please write using Arduino IDE.
// Make sure that the Adafruit_NeoPixel library has been installed.
#include <Adafruit_NeoPixel.h>
#define LED_PIN 4 // Signal pin for the LED Display.
#define LED_COUNT 10 // Number of LEDs in the LED Display.
Adafruit_NeoPixel strip(LED_COUNT, LED_PIN, NEO_RGB + NEO_KHZ800);
// Function used to create colorful effects
void setup() {
  strip.begin();
  strip.show();
  strip.setBrightness(127); //Set brightness to approximately 1/2 (maximum value = 255)
}
void loop() {
  strip.setPixelColor(0, 255, 0, 0); // Turn on D1-Red
  strip.setPixelColor(1, 255, 0, 0); // Turn on D3-Red
  strip.setPixelColor(8, 0, 0, 0); // Turn off
  strip.setPixelColor(9, 0, 0, 0); // Turn off
  strip.show(); // Update to display
  delay(500); // delay 0.5 seconds.
  strip.setPixelColor(0, 0, 0, 0); // Turn off
  strip.setPixelColor(1, 0, 0, 0); // Turn off
  strip.setPixelColor(8, 0, 255, 0); // Turn on D9-Green
  strip.setPixelColor(9, 0, 255, 0); // Turn on D10-Green
  strip.show(); // Update to display
  delay(500); // delay 0.5 seconds.
}
```



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder IR Reflow:

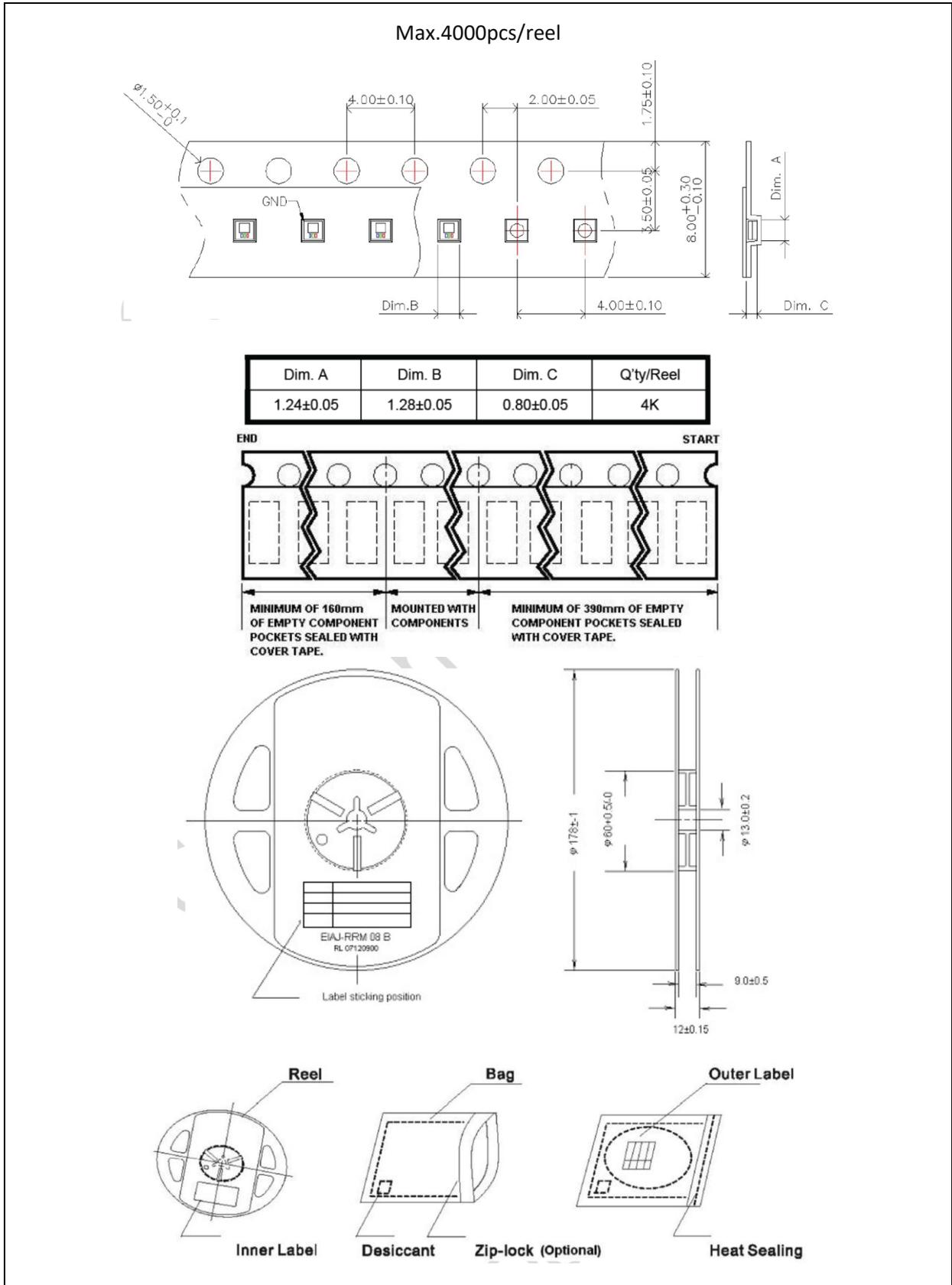


Note:

1. The maximum soldering temperature should be limited to 210°C, 5 sec. max.
2. Never take the next process until the component is cooled down to room temperature after reflow.
3. Maxima reflow soldering: 2 times.
4. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 72 hours. Otherwise, they should be kept in a damp-proof box with desiccating agent stored at R.H.<10% and apply baking before use.

Over-Current Proof:

Must apply resistors for protection otherwise slight voltage shift will cause big current change and burn-out will happen.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 12hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	17/02/2025	Datasheet set-up.
A1.1	15/05/2025	Revise MSL level.